



GN1A thru GN1M

Surface Mount Glass Passivated Rectifiers
Reverse Voltage 50V to 1000V Forward Current 1A

Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Built-in strain relief, ideal for automated placement
- Glass passivated chip junction
- High temperature soldering: 260°C/10 seconds at terminals



DO-214AC (SMA)

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	GN1A	GN1B	GN1D	GN1G	GN1J	GN1K	GN1M	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1						A	
Peak Forward Surge Current (8.3ms Single Half Sine-Wave Superimposed On Rated Load)	I_{FSM}	40				30			A
Typical Thermal Resistance ¹	$R_{\theta JA}$	68						$^\circ\text{C}/\text{W}$	
	$R_{\theta JL}$	10							
Operating Junction Temperature	T_J	-55 To +150						$^\circ\text{C}$	
Storage Temperature	T_{STG}	-55 To +150						$^\circ\text{C}$	

Notes:

1. Thermal resistance from junction to ambient and junction to lead mounted on FR4 P.C.B. with 0.2 x 0.2" (5.0 x 5.0mm) copper pads.

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	GN1A	GN1B	GN1D	GN1G	GN1J	GN1K	GN1M	Unit
Maximum Instantaneous Forward Voltage	V_F	$I_R=1\text{A}$	1.0						A	V
Maximum DC Reverse Current at Rated DC Blocking Voltag	I_R	$T_A=25^\circ\text{C}$	5						μA	
		$T_A=125^\circ\text{C}$	50							
Typical Reverse Recovery Time	t_{rr}	$I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$	1.8						μs	
Typical Junction Capacitance	C_J	4.0 V, 1 MHz	6.7						pF	

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

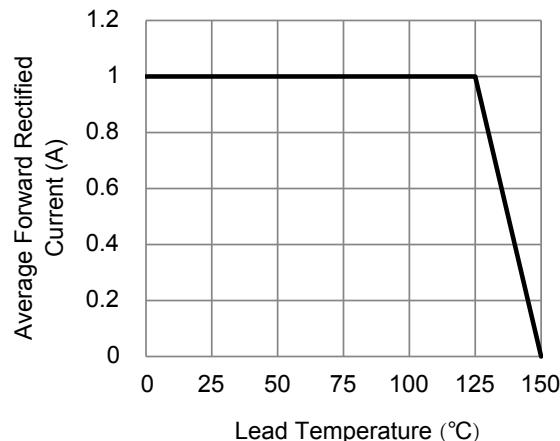


Figure 1. Forward Current Derating Curve

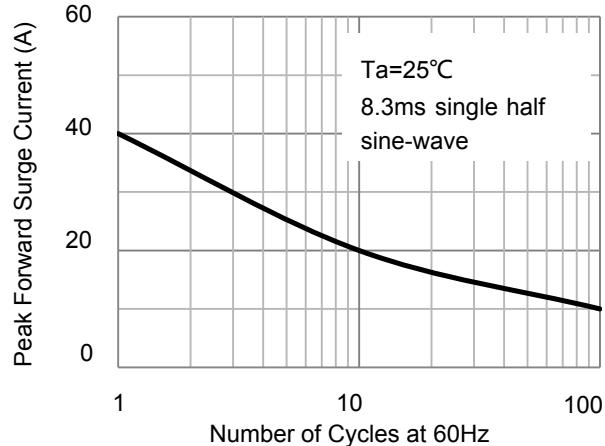


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

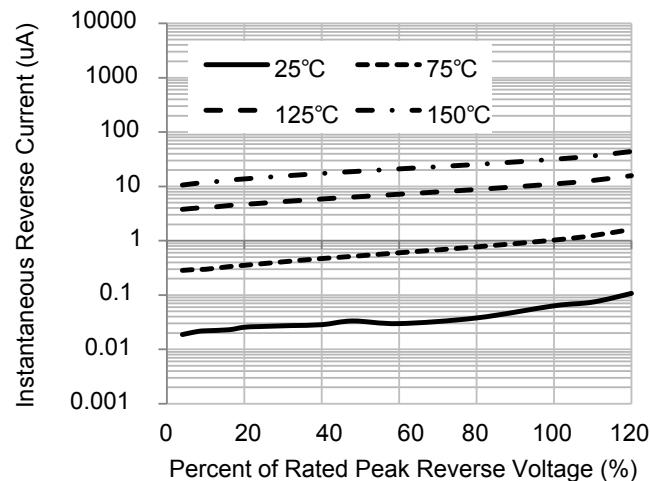


Figure 3. Typical Instantaneous Forward Characteristics

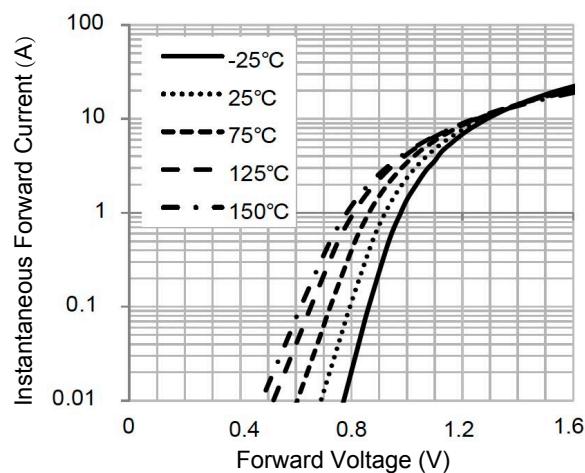


Figure 4. Typical Reverse Leakage Characteristics

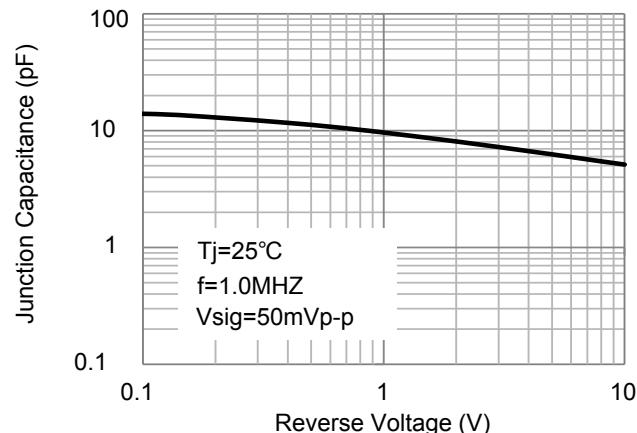
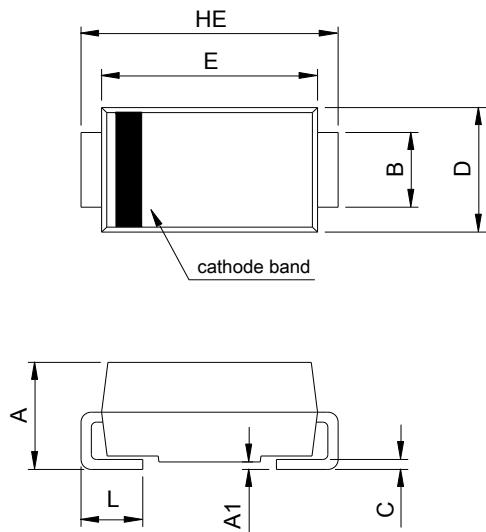


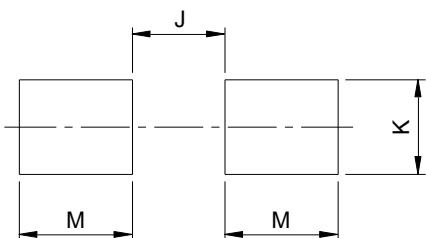
Figure 5. Typical Junction Capacitance

Package Outline Dimensions DO-214AC (SMA)



SMA (DO-214AC)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.90	2.30	0.075	0.091
A1	0.00	0.20	0.000	0.008
B	1.25	1.65	0.049	0.065
C	0.15	0.31	0.006	0.012
D	2.35	2.90	0.093	0.114
E	3.99	4.60	0.157	0.181
HE	4.80	5.30	0.189	0.209
L	0.76	1.52	0.030	0.060

Recommended Pad Layout



Recommended Pad Layout (Reference ONLY)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	2.20	-	0.087
K	1.72	-	0.068	-
M	2.00	-	0.079	-